



Integrated Device Technology, Inc.

# CMOS HIGH-SPEED STATIC RAM 72K (8K x 9-BIT) With Address Latches

PRELIMINARY  
INFORMATION  
IDT71569

### FEATURES:

- 8192-words x 9-bits organization
- Address Latch
- Fast access time:
  - Commercial: 20/25ns
  - Military: 25/35ns
- Battery backup operation – 2V data retention voltage (L-version only)
- Produced with advanced CEMOS™ high-performance technology
- Single 5V power supply
- Inputs and outputs directly TTL compatible
- Military product available compliant to MIL-STD-883, Class B
- JEDEC standard 28-pin DIP and SOJ plastic packages

### DESCRIPTION:

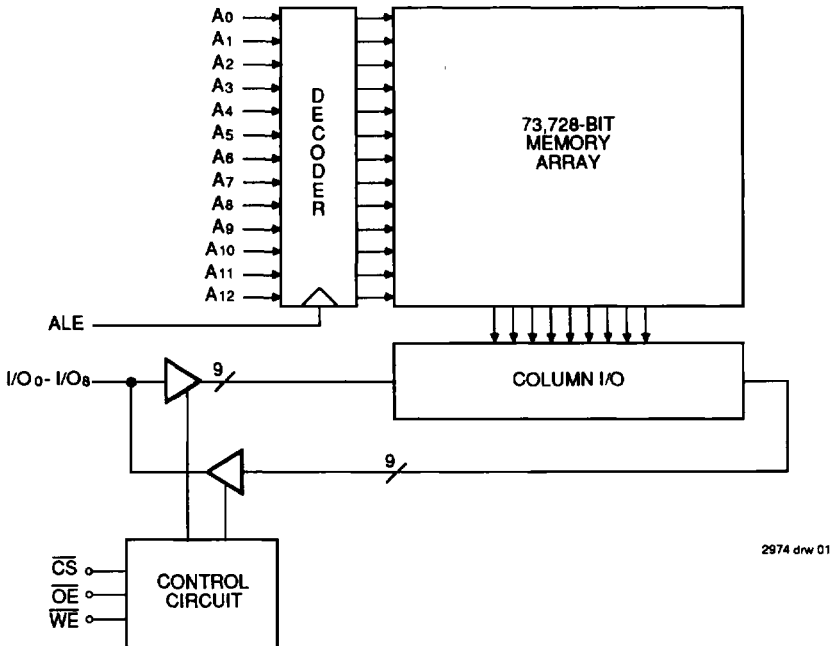
The IDT71569 is a 73,728-bit high-speed static RAM, organized as 8K x 9, with address latches. It is fabricated using IDT's high-performance, high-reliability CEMOS technology.

The IDT71569 offers address access times as fast as 10ns. The ninth bit is optimal for systems using parity. This device is ideally suited for cache memory applications.

All inputs and outputs of the IDT71569 are TTL-compatible. The IDT71569 is packaged in an industry standard 300-mil 28-pin DIP and SOJ plastic packages.

Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B, making it ideally

### FUNCTIONAL BLOCK DIAGRAM



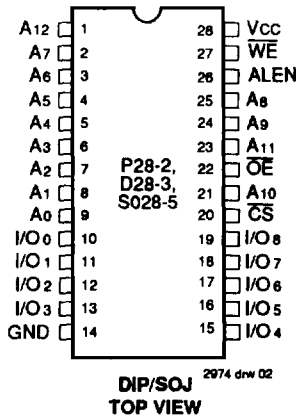
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MILITARY AND COMMERCIAL TEMPERATURE RANGES

DECEMBER 1990

**PIN CONFIGURATION**



**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

Symbol	Rating	Com'l.	Mil.	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
TA	Operating Temperature	0 to +70	-55 to +125	°C
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	°C
TSTG	Storage Temperature	-55 to +125	-65 to +150	°C
IOUT	DC Output Current	50	50	mA

**NOTE:** <sup>2974 tbl 02</sup>  
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**TRUTH TABLE<sup>(1)</sup>**

ALE	$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	I/O	Function
X	H	X	X	Hi-Z	Deselect chip
H	X	X	X	X	Address Latch Transparent
L	X	X	X	X	Address Latch Closed
H	L	L	H	DOUT	Read From Current Address
L	L	L	H	DOUT	Read From Latched Address
H	L	X	L	DIN	Write to Current Address
L	L	X	L	DIN	Write to Latched Address
X	L	H	H	Hi-Z	Outputs Disabled

**NOTE:** <sup>2974 tbl 01</sup>  
1. H = V<sub>IH</sub>, L = V<sub>IL</sub>, X = Don't Care.

**CAPACITANCE (TA = +25°C, f = 1.0MHz)**

Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
CIN	Input Capacitance	V <sub>IN</sub> = 0V	8	pF
COUT	Output Capacitance	V <sub>OUT</sub> = 0V	8	pF

**NOTE:** <sup>2974 tbl 03</sup>  
1. This parameter is determined by device characterization, but is not production tested.

**RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE**

Grade	Temperature	GND	Vcc
Military	-55°C to +125°C	0V	5V ± 10%
Commercial	0°C to +70°C	0V	5V ± 10%

<sup>2974 tbl 04</sup>

**RECOMMENDED DC OPERATING CONDITIONS**

Symbol	Parameter	Min.	Typ.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
V <sub>IH</sub>	Input High Voltage	2.2	—	6.0	V
V <sub>IL</sub>	Input Low Voltage	-0.5 <sup>(1)</sup>	—	0.8	V

**NOTE:** <sup>2974 tbl 05</sup>  
1. V<sub>IL</sub> (min.) = -3.0V for pulse width less than 20ns.

**DC ELECTRICAL CHARACTERISTICS<sup>(1)</sup>**

(VCC = 5.0V ± 10%, VLC = 0.2V, VHC = VCC - 0.2V)

Symbol	Parameter	Power	71569S20 <sup>(3)</sup> 71569L20 <sup>(3)</sup>		71569S25 71569L25		71569S35 <sup>(4)</sup> 71569L35 <sup>(4)</sup>		Unit
			Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	
Icc1	Operating Power Supply Current $\overline{CS} = V_{IL}$ , Outputs Open, VCC = Max., f = 0 <sup>(2)</sup>	S	90	—	90	100	—	100	mA
		L	80	—	80	90	—	90	
Icc2	Dynamic Operating Current $\overline{CS} = V_{IL}$ , Outputs Open, VCC = Max., f = fMAX <sup>(2)</sup>	S	180	—	170	190	—	160	mA
		L	160	—	150	170	—	140	
ISB	Standby Power Supply Current (TTL Level) $\overline{CS} \geq V_{IH}$ , Outputs Open, VCC = Max., f = fMAX <sup>(2)</sup>	S	20	—	20	20	—	20	mA
		L	3	—	3	5	—	5	
ISB1	Full Standby Power Supply Current (CMOS Level) $\overline{CS} \geq V_{HC}$ , VCC = Max., VIN ≥ VHC or VIN ≤ VHC, f = 0 <sup>(2)</sup>	S	15	—	15	20	—	20	mA
		L	0.2	—	0.2	1.0	—	1.0	

**NOTES:**

1. All values are maximum guaranteed values.
2. At f = fMAX address and data inputs are cycling at the maximum frequency of read cycles of 1/trc. f = 0 means no input lines change.
3. 0° to +70° C. temperature range only.
4. -55° to +125° C. temperature range only.

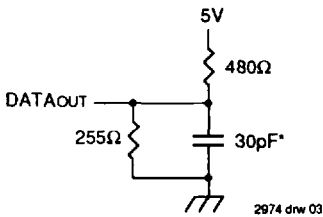
2974 tbl 06

**AC TEST CONDITIONS**

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figures 1 and 2

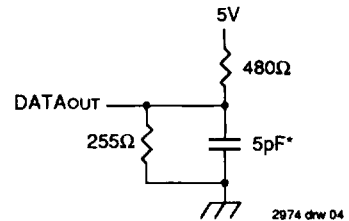
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2974 drw 03

Figure 1. Output Load



2974 drw 04

Figure 2. Output Load  
(for tCLZ, tOLZ, tCHZ, tOHZ, tLOW, tWHZ)

\*Includes scope and jig capacitances

**DC ELECTRICAL CHARACTERISTICS**

Vcc = 5.0V ± 10%

Symbol	Parameter	Test Condition		IDT7169S		IDT7169L		Unit
				Min.	Max.	Min.	Max.	
I <sub>LI</sub>	Input Leakage Current	Vcc = Max., VIN = GND to Vcc	MIL COM'L	— —	10 5	— —	5 2	μA
I <sub>LO</sub>	Output Leakage Current	Vcc = Max., CS = VIH, VOUT = GND to Vcc	MIL COM'L	— —	10 5	— —	5 2	μA
VOL	Output Low Voltage	IOL = 8mA, Vcc = Min. IOL = 10mA, Vcc = Min.		— —	0.4 0.5	— —	0.4 0.5	V
VOH	Output High Voltage	IOH = -4mA, Vcc = Min.		2.4	—	2.4	—	V

2974 tbl 08

**DATA RETENTION CHARACTERISTICS OVER ALL TEMPERATURE RANGES**

(L Version Only) VLc = 0.2V, VHC = Vcc - 0.2V

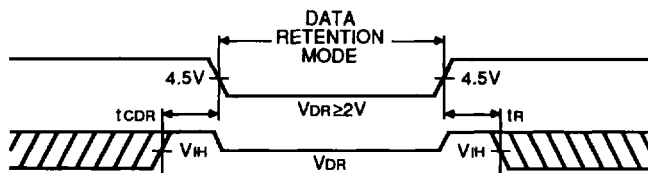
Symbol	Parameter	Test Condition	Min.	Typical <sup>(1)</sup> Vcc @		Maximum Vcc @		Unit
				2.0V	3.0V	2.0V	3.0V	
VDR	Vcc for Data Retention	—	2.0	—	—	—	—	V
I <sub>CCDR</sub>	Data Retention Current	MIL. COM'L.	— —	10 10	15 15	200 60	300 90	μA
t <sub>CDR</sub> <sup>(3)</sup>	Chip Deselect to Data Retention Time	CS ≥ VHC VIN ≥ VHC or ≤ VLc	0	—	—	—	—	ns
t <sub>IR</sub> <sup>(3)</sup>	Operation Recovery Time		t <sub>RC</sub> <sup>(2)</sup>	—	—	—	—	ns
I <sub>LI</sub>   <sup>(3)</sup>	Input Leakage Current	—	—	—	—	2	2	μA

**NOTES:**

1. TA = +25°C.
2. t<sub>RC</sub> = Read Cycle Time.
3. This parameter is guaranteed, but not tested.

2974 tbl 09

**LOW Vcc DATA RETENTION WAVEFORM**



**AC ELECTRICAL CHARACTERISTICS** (V<sub>CC</sub> = 5.0V ± 10%, All Temperature Ranges)

Symbol	Parameter	71569S20 <sup>(1)</sup> 71569L20 <sup>(1)</sup>		71569S25 71569L25		71569S35 <sup>(4)</sup> 71569L35 <sup>(4)</sup>		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
		<b>Read Cycle</b>						
t <sub>RC</sub>	Read Cycle Time	20	—	25	—	35	—	ns
t <sub>AA</sub>	Address Access Time <sup>(3)</sup>	—	19	—	25	—	35	ns
t <sub>ALA</sub>	Address Latch Access Time	—	20	—	25	—	35	ns
t <sub>ACS</sub>	Chip Select Access Time	—	20	—	25	—	35	ns
t <sub>CLZ</sub>	Chip Select to Output in Low Z <sup>(2)</sup>	3	—	3	—	3	—	ns
t <sub>OE</sub>	Output Enable to Output Valid	—	8	—	12	—	18	ns
t <sub>OLZ</sub>	Output Enable to Output in Low Z <sup>(2)</sup>	3	—	3	—	3	—	ns
t <sub>CHZ</sub>	ChipSelect to Output High Z <sup>(2)</sup>	—	13	—	15	—	25	ns
t <sub>OHZ</sub>	Output Disable to Output in High Z <sup>(2)</sup>	—	10	—	15	—	20	ns
t <sub>OH</sub>	Output Hold from Address Change	5	—	5	—	5	—	ns
t <sub>CH</sub>	ALEN High Time	10	—	10	—	10	—	ns
t <sub>CL</sub>	ALEN Low Time	10	—	10	—	10	—	ns
t <sub>AS</sub>	Address Set-up Time to Address Latch Enable	5	—	5	—	5	—	ns
t <sub>AH</sub>	Address Hold Time to Address Latch Enable	3	—	5	—	7	—	ns
<b>Write Cycle</b>								
t <sub>WC</sub>	Write Cycle Time	20	—	25	—	35	—	ns
t <sub>AW</sub>	Address Valid to End of Write <sup>(3)</sup>	15	—	18	—	25	—	ns
t <sub>CW</sub>	Chip Select to End of Write	15	—	18	—	25	—	ns
t <sub>AS</sub>	Address Set-up Time	0	—	0	—	0	—	ns
t <sub>WP</sub>	Write Pulse Width	15	—	21	—	25	—	ns
t <sub>WR</sub>	Write Recovery Time <sup>(3)</sup>	0	—	0	—	0	—	ns
t <sub>WHZ</sub>	Write Enable to Output in High Z <sup>(2)</sup>	—	8	—	10	—	14	ns
t <sub>DW</sub>	Data Valid to End of Write	10	—	13	—	15	—	ns
t <sub>DH</sub>	Data Hold Time from Write	0	—	0	—	0	—	ns
t <sub>OW</sub>	Output Active from End of Write <sup>(2)</sup>	5	—	5	—	5	—	ns
t <sub>CH</sub>	ALEN High Time	10	—	10	—	10	—	ns
t <sub>CL</sub>	ALEN Low Time	10	—	10	—	10	—	ns
t <sub>AS</sub>	Address Set-up Time to Address Latch Enable	5	—	5	—	5	—	ns
t <sub>AH</sub>	Address Hold Time to Address Latch Enable	5	—	5	—	5	—	ns

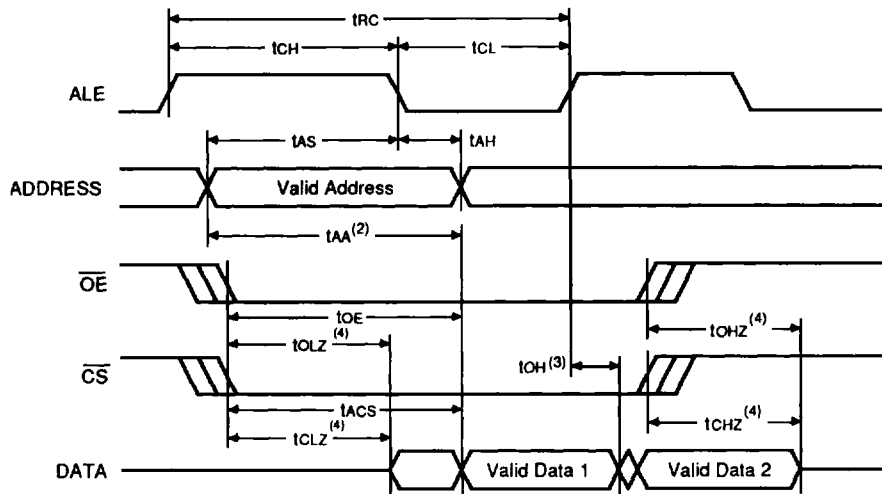
**NOTES:**

- 0° to +70°C temperature range only.
- This parameter is guaranteed, but not tested.
- This measurement depends on the combination of ALEN high plus an address change. This combination may either happen at the rising edge of ALEN, or during an address change after ALEN has become high.
- 55° to +125° C. temperature range only.

2974 tbl 10

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**TIMING WAVEFORM OF READ CYCLE (1)**

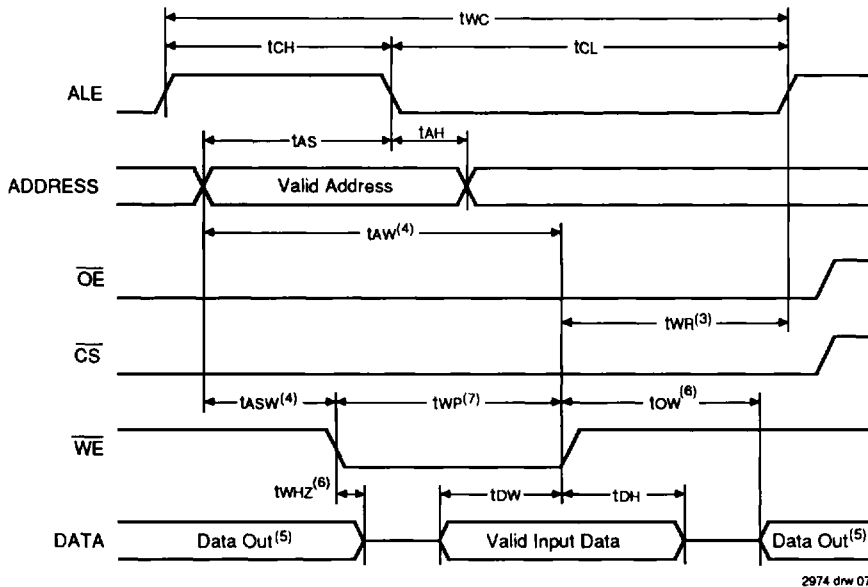


2974 drw 06

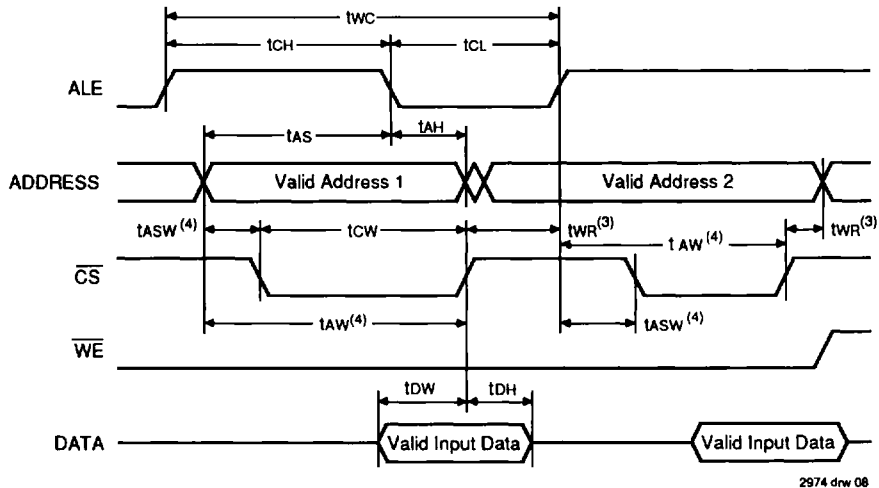
**NOTES:**

1. WE is high throughout a read cycle.
2. The parameter tAA is measured either from the first low to high transition of ALEN after the read address has become valid, or from the stabilization of the read address during the period when ALEN is high, whichever occurs last.
3. The parameter tOH is measured either from the first low to high transition of ALEN after an address change, or from an address change during the period when ALEN is high, whichever occurs first.
4. Transition is measured ±200mV from steady state with a 5pF load (including scope and jig).

**TIMING WAVEFORM OF WRITE CYCLE NO. 1 ( $\overline{WE}$  CONTROLLED)<sup>(1,2)</sup>**



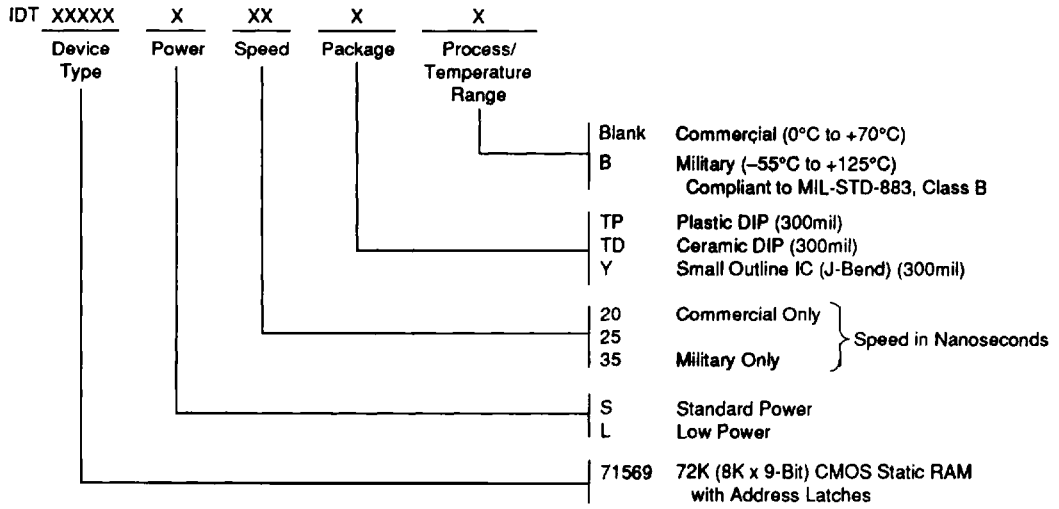
**TIMING WAVEFORM OF WRITE CYCLE NO. 2 ( $\overline{CS}$  CONTROLLED)<sup>(1,2)</sup>**



**NOTES:**

1.  $\overline{WE}$  or  $\overline{CE}$  must be high during all address transitions.
2. A write occurs during the overlap ( $t_{BW}$ ,  $t_{CW}$  or  $t_{WP}$ ) of a low  $\overline{CE}$  and a low  $\overline{WE}$ .
3. The parameter  $t_{WR}$  is measured from the earlier of  $\overline{CE}$  or  $\overline{WE}$  going high either to the first low to high transition of  $\overline{ALEN}$  after an address change, or to an address change during the period when  $\overline{ALEN}$  is high, whichever occurs last.
4. The parameters  $t_{ASW}$  and  $t_{AW}$  are measured either from the first low to high transition of  $\overline{ALEN}$  after an address change has become valid, or from the stabilization of the valid write address during the period when  $\overline{ALEN}$  is high, whichever occurs first.
5. During this period, the I/O pins are in the output state so that the input signals must not be applied.
6. This transition is measured  $\pm 200\text{mV}$  from steady state with a 5pF load (including scope and jig).
7. If  $\overline{OE}$  is low during a  $\overline{WE}$  controlled write cycle, the write pulse width must be the larger of  $t_{WP}$  or  $(t_{WHZ} + t_{WP})$  to allow the I/O drivers to turn off and data to be placed on the bus for the required  $t_{DW}$ . If  $\overline{OE}$  is high during a  $\overline{WE}$  controlled write cycle, this requirement does not apply and the write pulse can be as short as the specified  $t_{WP}$ .

**ORDERING INFORMATION**



2974 drw 09